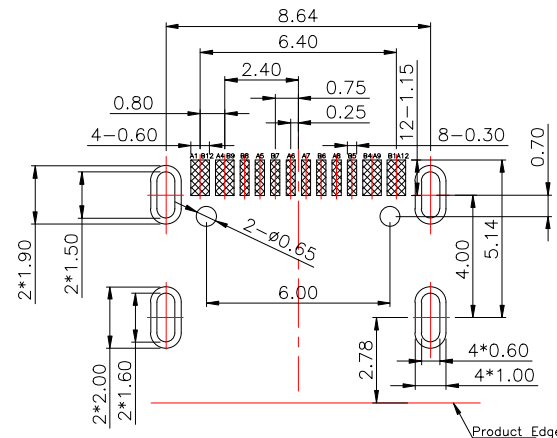
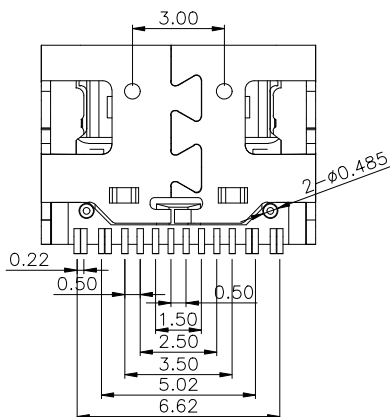
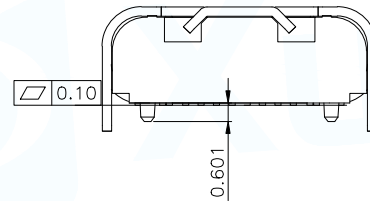
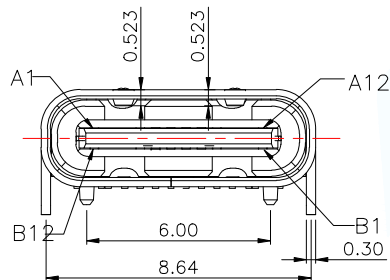
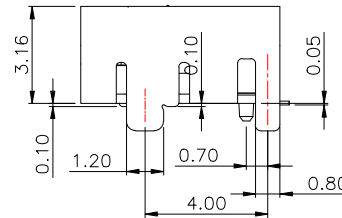
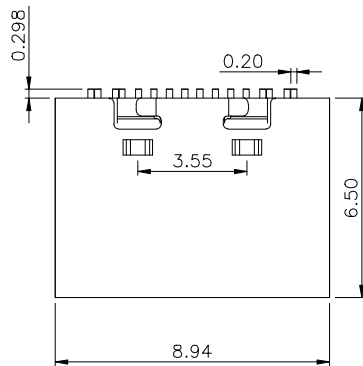




RECOMMENDED P.C.B. LAYOUT
TOLERANCE UNSPECIFIED $\pm 0.05\text{mm}$

NOTE:

1.MATERIAL SPECIFICATION:

1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.

2.CONTACTS:C7025

3.MID PLATE: STAINLESS STEEL

4.FRONT SHELL: STAINLESS STEEL

2.PLATING SPECIFICATION:

2-1.CONTACTS:

Ni 50u" MIN. UNDER PLATED OVER ALL.

Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.

(GOLD PLATING THICKNESS FOLLOW THE P/N)

PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N

2-2.FRONT SHELL:

Ni 30u" MIN. UNDER PLATED OVER ALL.

2-3.MID PLATE:

CLEAR ONLY

3.MECHANICAL PERFORMANCE,

3-1.INSERTION FORCE: 0.5~2.0kgf.

3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.

3-3.DURABILITY: 10000 CYCLES.

4.ELECTRICAL PERFORMANCE,

4-1. CURRENT RATING:3.0A

VOLTAGE RATING:5.0V

4-2. LLCR:

VBUS & GND PINS AND OTHER PINS: 40mA/PIN MAX.

SHIELD: 50mA/MAX.

LLCR MAX. CHANGE OF ALL PINS: 10mA.

4-3.INSULATION RESISTANCE: 100M Ω MIN

4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

5. ENVIRONMENTAL PERFORMANCE:

OPERATING TEMPERATURE: -25°C~+85°C.

6.IR REFLOW:

THE PEAK TEMPERATURE ON THE BOARD SHALL

BE MAINTAINED FOR 10 SECONDS AT 260°C.

PIN ASSINGMENT											
A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12
GND	\	\	VBUS	CC1	Dp1	Dn1	SBU1	VBUS	\	\	GND
GND	\	\	VBUS	SBU2	Dn2	Dp2	CC2	VBUS	\	\	GND
B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1

3	SHELL	STAINLESS STEEL	Ni/Cu Plated	1PCS
2	CONTACT	C7025	Contactarea G/F 1U/3U"	1SET
1	MD	HIGH TEMPERATURE PLASTIC	BLACK	1PCS
NO.	DESCRIPTION	MATERIAL	REMARKS	QTY

MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			
DECIMALS:	ANGLES:	PAR	TYPEC-309-ACP16L65
.X:±0.25	X":±2°	DWN	
.XX:±0.15	X.X":±0.5°	CHKD	
.XXX:±0.10		APVD	
CUSTOMER COPY		SCALE1:1	UNIT:MM
		SIZE:A4	UNIT:MM
		SHEET:1F1	REV:A